



STP60NF03L

N-channel 30V - 0.008Ω - 60A TO-220
STripFET™ Power MOSFET

General features

| Type | V _{DSS} | R _{DS(on)} | I _D |
|------------|------------------|---------------------|----------------|
| STP60NF03L | 30V | <0.01Ω | 60A |

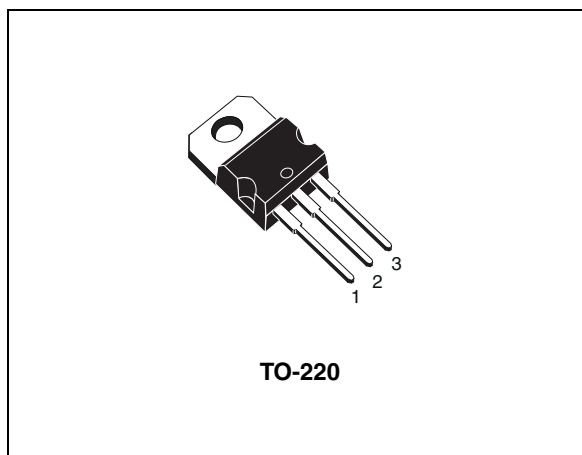
- Low threshold drive

Description

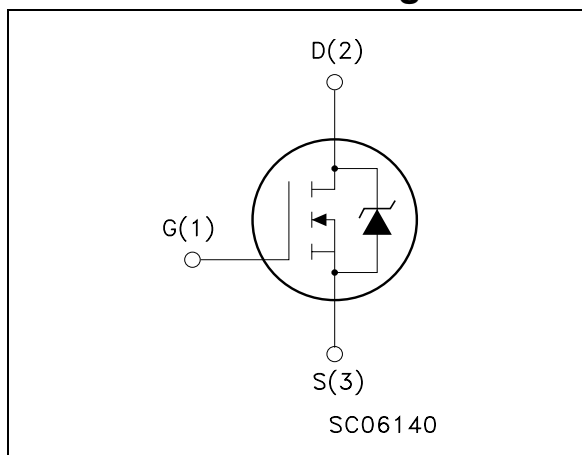
This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Applications

- Switching application



Internal schematic diagram



Order codes

| Part number | Marking | Package | Packaging |
|-------------|----------|---------|-----------|
| STP60NF03L | P60NF03L | TO-220 | Tube |

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1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|--------------------|--|-------------------|---------------------|
| V_{GS} | Gate-source voltage | 30 | V |
| V_{DGR} | Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$) | 30 | V |
| V_{GS} | Gate- source Voltage | ± 20 | V |
| I_D | Drain current (continuous) at $T_C = 25^\circ\text{C}$ | 60 | A |
| I_D | Drain current (continuous) at $T_C=100^\circ\text{C}$ | 42 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 240 | A |
| P_{TOT} | Total dissipation at $T_C = 25^\circ\text{C}$ | 100 | W |
| | Derating factor | 0.67 | W/ $^\circ\text{C}$ |
| $E_{AS}^{(2)}$ | Single pulse avalanche energy | 650 | mJ |
| T_J T_{stg} | Operating junction temperature Storage temperature | 175 -65 to 175 | $^\circ\text{C}$ |

1. Pulse width limited by safe operating area
2. Starting $T_j = 25^\circ\text{C}$, $I_D = 30\text{A}$, $V_{DD} = 20\text{V}$

Table 2. Thermal data

| | | | |
|----------------|--|------|---------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case Max | 1.5 | $^\circ\text{C}/\text{W}$ |
| R_{thj-a} | Thermal resistance junction-ambient Max | 62.5 | $^\circ\text{C}/\text{W}$ |
| $R_{thc-sink}$ | Thermal resistance case-sink typ | 0.5 | $^\circ\text{C}/\text{W}$ |
| T_l | Maximum lead temperature for soldering purpose | 300 | $^\circ\text{C}$ |

2 Electrical characteristics

($T_{CASE}=25^{\circ}C$ unless otherwise specified)

Table 3. On/off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|--|--|------|-----------------|----------------|----------------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $I_D = 250 \mu A, V_{GS} = 0$ | 30 | | | V |
| I_{DSS} | Zero gate voltage drain current ($V_{GS} = 0$) | $V_{DS} = \text{Max rating},$ $V_{DS} = \text{Max rating} @ 125^{\circ}C$ | | | 1 10 | μA μA |
| I_{GSS} | Gate body leakage current ($V_{DS} = 0$) | $V_{GS} = \pm 20V$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1 | 1.5 | 2.5 | V |
| $R_{DS(on)}$ | Static drain-source on resistance | $V_{GS} = 10V, I_D = 30A$ $V_{GS} = 4.5V, I_D = 30A$ | | 0.008 0.0095 | 0.010 0.015 | Ω Ω |

Table 4. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|---|---|------|--------------------|------|----------------|
| $g_{fs}^{(1)}$ | Forward transconductance | $V_{DS} > I_{D(on)} \times R_{DS(on)max},$ $I_D = 30A$ | | 60 | | S |
| C_{iss} C_{oss} C_{rss} | Input capacitance Output capacitance Reverse transfer capacitance | $V_{DS} = 25V, f = 1 \text{ MHz},$ $V_{GS} = 0$ | | 2550 630 215 | | pF pF pF |
| $t_{d(on)}$ t_r | Turn-on Delay Time Rise Time | $V_{DD} = 15V, I_D = 30A,$ $R_G = 4.7\Omega, V_{GS} = 4.5V$ (see Figure 12) | | 40 250 | | ns ns |
| Q_g Q_{gs} Q_{gd} | Total gate charge Gate-source charge Gate-drain charge | $V_{DD} = 24V, I_D = 60A$ $V_{GS} = 5V$ | | 43 12 21 | 58 | nC nC nC |

1. Pulsed: pulse duration=300 μs , duty cycle 1.5%

Table 5. Source drain diode

| Symbol | Parameter | Test conditions | Min | Typ. | Max | Unit |
|-----------------------------------|--|--|-----|------------------|-----|--------------------|
| I_{SD} | Source-drain current | | | | 60 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | | | 240 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD}=60A, V_{GS}=0$ | | | 1.5 | V |
| t_{rr} Q_{rr} I_{RRM} | Reverse recovery time Reverse recovery charge Reverse recovery current | $I_{SD}=60A,$ $di/dt = 100A/\mu s,$ $V_{DD}=15V, T_j=150^\circ C$ (see Figure 14) | | 75 100 2.6 | | ns μC A |

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

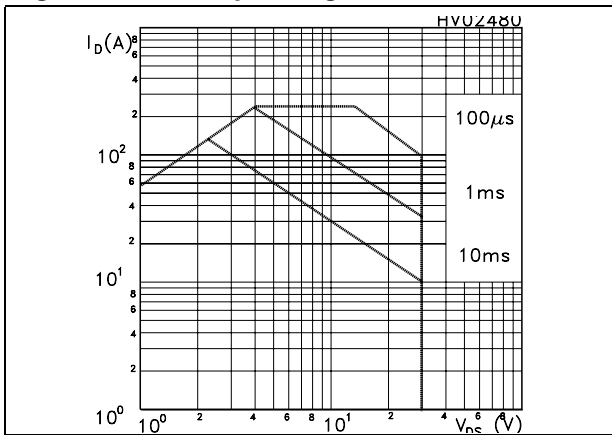


Figure 2. Thermal impedance

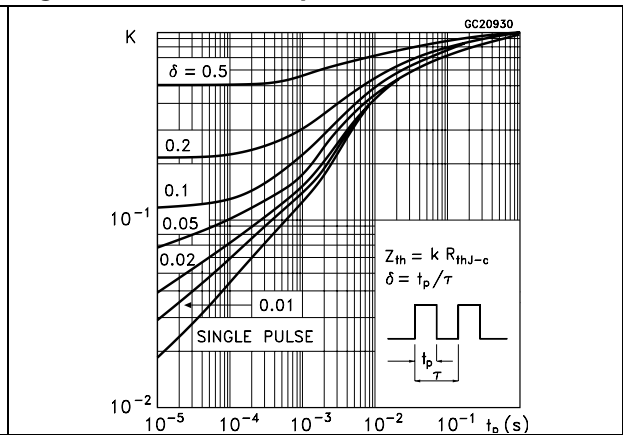


Figure 3. Output characteristics

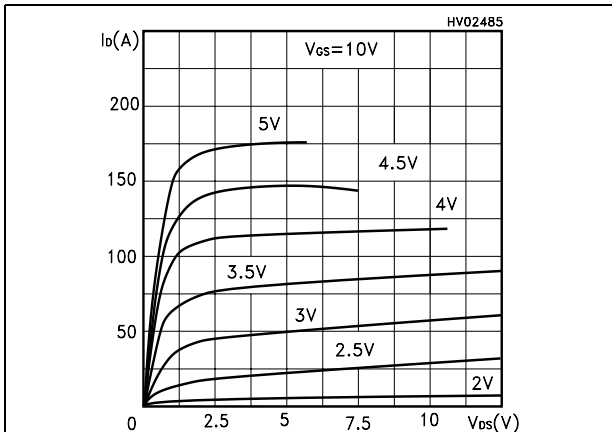


Figure 4. Transfer characteristics

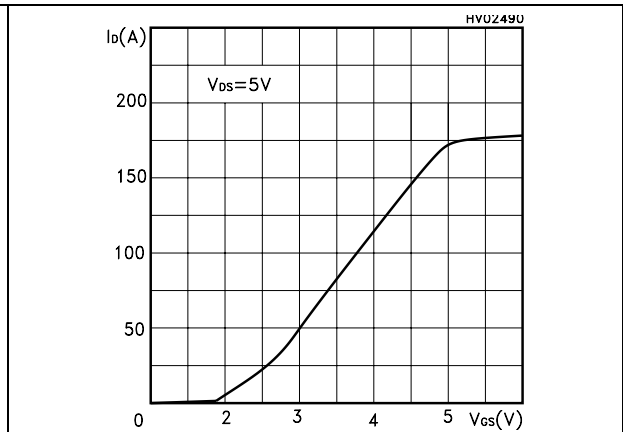


Figure 5. Transconductance

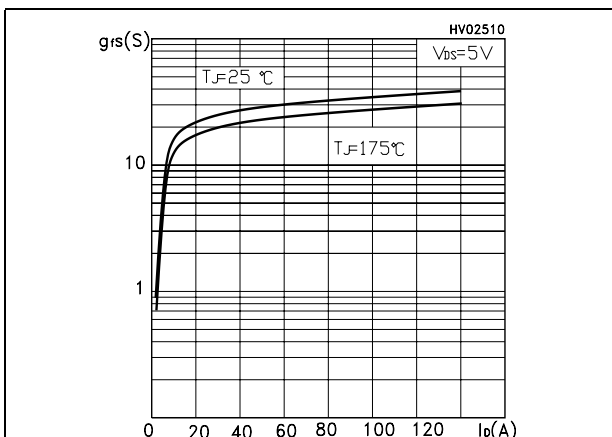


Figure 6. Static drain-source on resistance

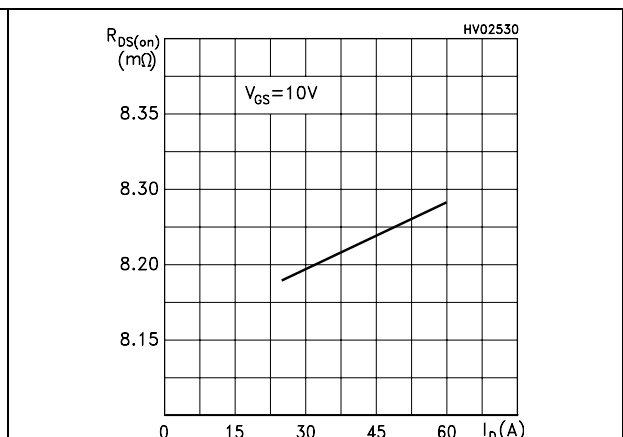


Figure 7. Gate charge vs gate-source voltage Figure 8. Capacitance variations

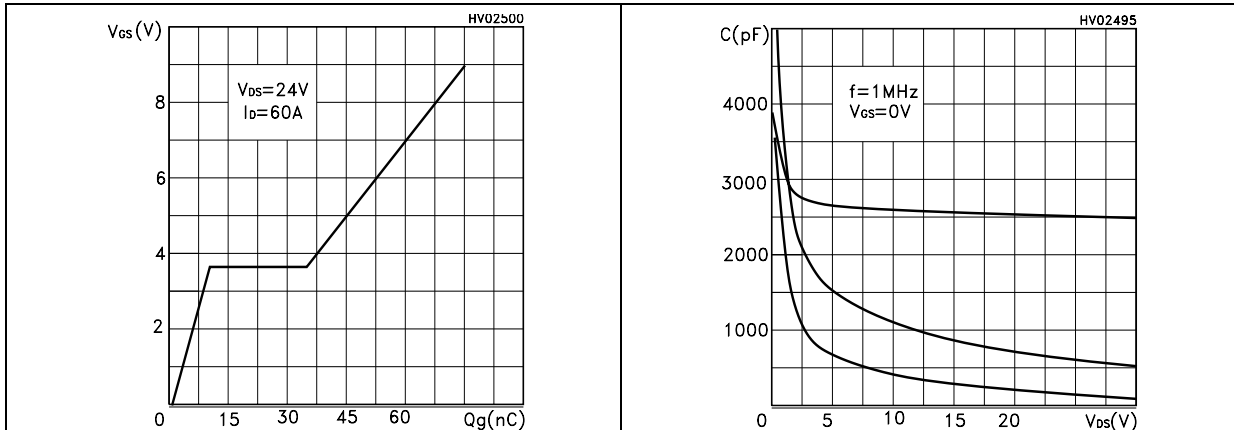


Figure 9. Normalized gate threshold voltage vs temperature Figure 10. Normalized on resistance vs temperature

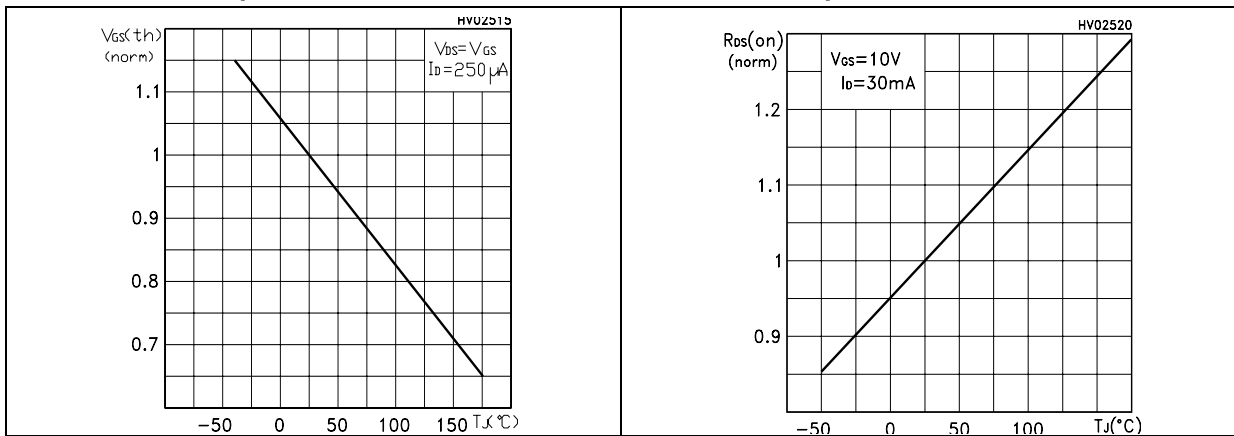
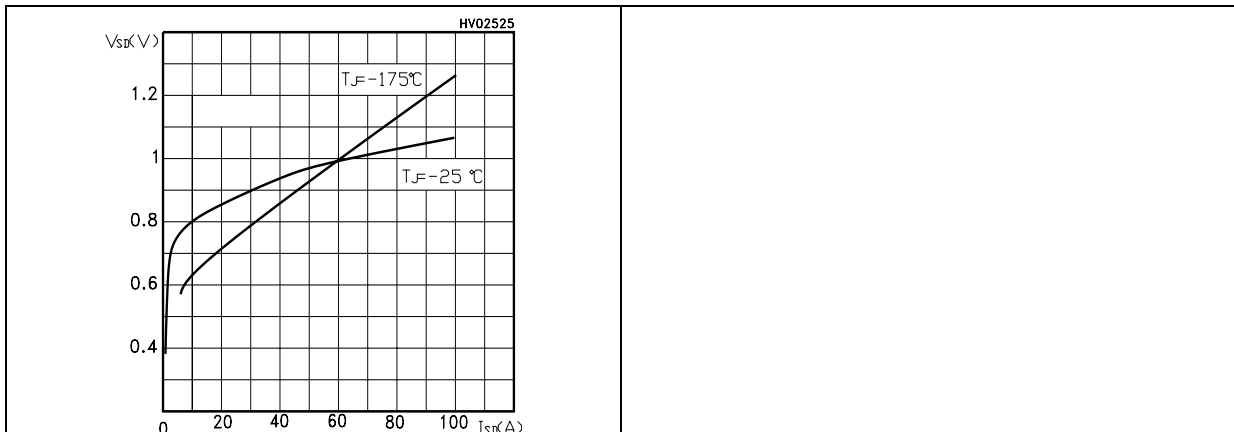


Figure 11. Source-drain diode forward characteristics



3 Test circuit

Figure 12. Switching times test circuit for resistive load

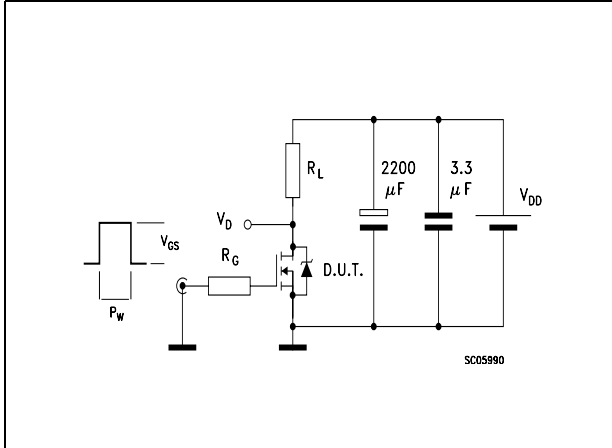


Figure 13. Gate charge test circuit

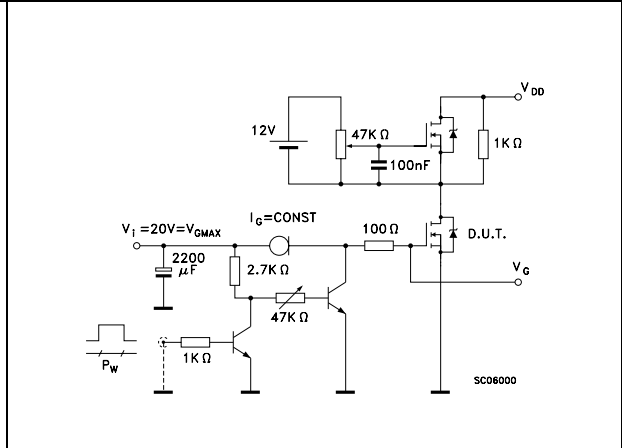


Figure 14. Test circuit for inductive load switching and diode recovery times

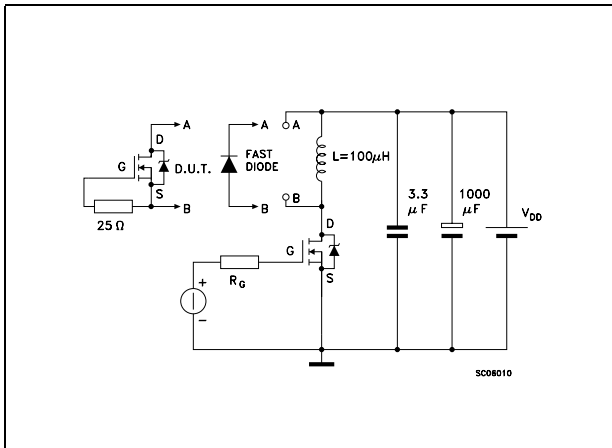


Figure 15. Unclamped Inductive load test circuit

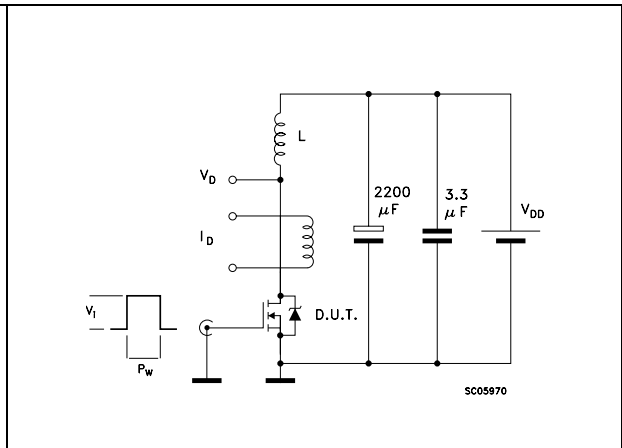


Figure 16. Unclamped inductive waveform

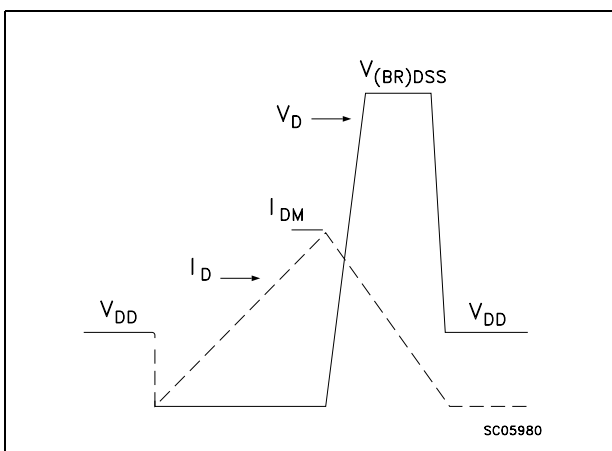
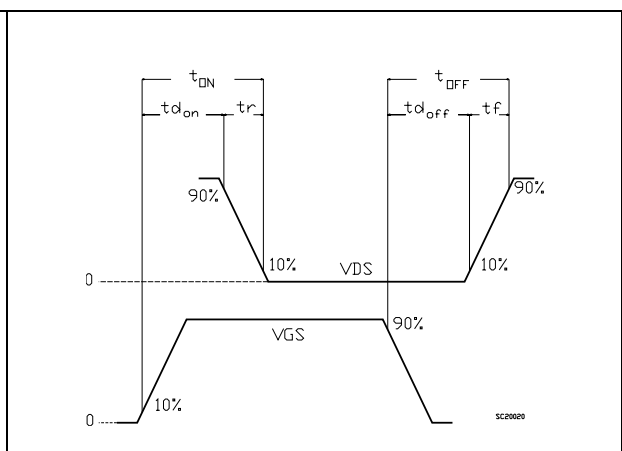


Figure 17. Switching time waveform

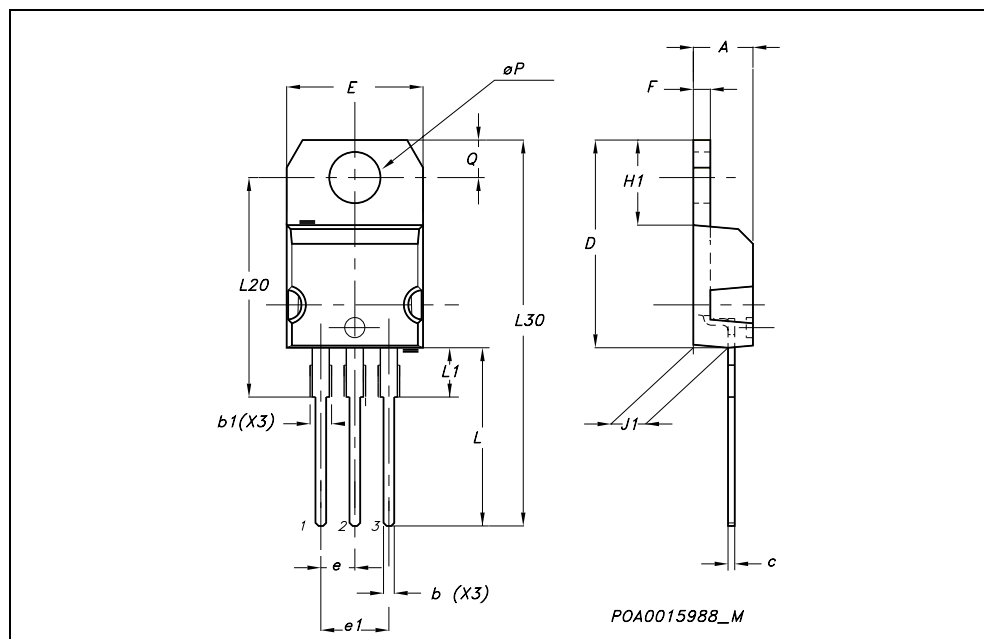


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-220 MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|-------|-------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.40 | | 4.60 | 0.173 | | 0.181 |
| b | 0.61 | | 0.88 | 0.024 | | 0.034 |
| b1 | 1.15 | | 1.70 | 0.045 | | 0.066 |
| c | 0.49 | | 0.70 | 0.019 | | 0.027 |
| D | 15.25 | | 15.75 | 0.60 | | 0.620 |
| E | 10 | | 10.40 | 0.393 | | 0.409 |
| e | 2.40 | | 2.70 | 0.094 | | 0.106 |
| e1 | 4.95 | | 5.15 | 0.194 | | 0.202 |
| F | 1.23 | | 1.32 | 0.048 | | 0.052 |
| H1 | 6.20 | | 6.60 | 0.244 | | 0.256 |
| J1 | 2.40 | | 2.72 | 0.094 | | 0.107 |
| L | 13 | | 14 | 0.511 | | 0.551 |
| L1 | 3.50 | | 3.93 | 0.137 | | 0.154 |
| L20 | | 16.40 | | | 0.645 | |
| L30 | | 28.90 | | | 1.137 | |
| øP | 3.75 | | 3.85 | 0.147 | | 0.151 |
| Q | 2.65 | | 2.95 | 0.104 | | 0.116 |



5 Revision history

Table 6. Revision history

| Date | Revision | Changes |
|-------------|-----------------|---------------------------------|
| 09-Sep-2004 | 3 | Complete document |
| 09-Aug-2006 | 4 | New template, no content change |

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